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Date:	24/04/2014
P/N:	PCB000946
Layers:	4
Total Thickness:	1.6mm±10%
Finish:	Immersion silver

Stack-up and impedance requirements

Material:	FR4-High TG
PCB size and PCB units per array	25.0mm x 129.0mm; Four units per array
PCB Utilization (%)	
Gold finger:	No
Back drill depth/width types on CS:	0
Back drill depth/width types on PS:	0



All dimensions are in mils unless otherwise stated

Layer	Copper parameters				Resin parameters				Impedance parameters							
	signal/ Power/ GND	Copper weight [oz]	Copper thickness after plating [Mil]	Copper roughness	Dielectric thickness	Material	Glass type	Resin content [%]	Differential pairs parameters					SE signal parameters		
									Imp. [Ω]	Default		Neck-down		Imp.[Ω]	Default Width	Neck-down Width
Layer 1 - CS	Power	2	3.4													
Core			20		>4	FR4-HIGH TG	EM827 Core 20mil									
Layer 2	Signal	2								NA	NA	NA	NA	50±10%	7.8	NA
Pre - PEG			7.3		>4	FR4-HIGH TG	EM827 PP 1080X3 (7.3mil)									
Layer 3	Power	2								NA	NA	NA	NA	50±10%	7.8	NA
Core			20		>4	FR4-HIGH TG	EM827 Core 20mil									
Layer 4 - PS	Signal	2	3.4													
If you have any queries please do not hesitate to contact: Shay Madar, HW engineer, Cell: +972 (54) 4352010 shaym@mellanox.com								Revision control:								
								Revision	Date	Description						
								00	24/04/2014	Tape out release						

Notes:

1	The dielectric thickness, line widths and differential space values are nominal values. Minor changes can be done to meet the impedance requirements.(HW designer approval is a must)
2	Trace widths are nominal finished dimensions.